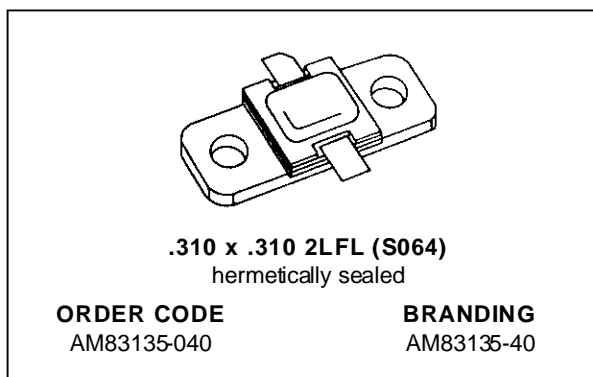


## RF & MICROWAVE TRANSISTORS S-BAND RADAR APPLICATIONS

PRELIMINARY DATA

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- P<sub>OUT</sub> = 40 W MIN. WITH 5.1 dB GAIN

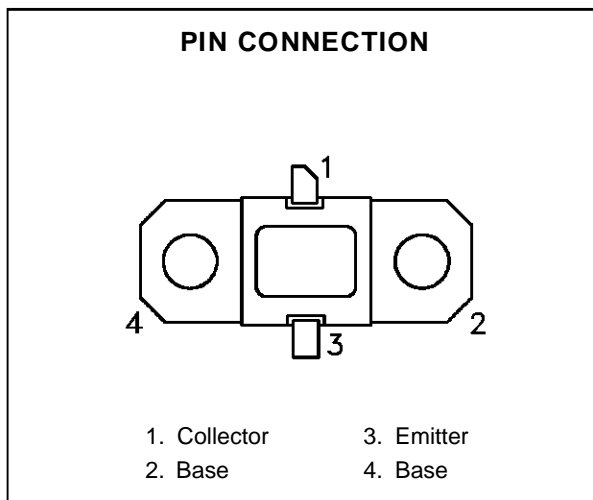


### DESCRIPTION

The AM83135-040 device is a high power silicon bipolar NPN transistor specifically designed for S-Band radar pulsed output and driver applications.

This device is characterized at 10μsec pulse width and 10% duty cycle, but is capable of operation over a range of pulse widths, duty cycles, and temperatures, and can withstand a 3:1 output VSWR with a + 1 dB input overdrive. Low RF thermal resistance, refractory/gold metallization, and computerized automatic wire bonding techniques ensure high reliability and product consistency (including phase characteristics).

The AM83135-040 is supplied in the IMPAC™ Hermetic Metal/Ceramic package with internal Input/Output impedance matching circuitry, and is intended for military and other high reliability applications.



### ABSOLUTE MAXIMUM RATINGS (T<sub>case</sub> = 25°C)

Symbol	Parameter	Value	Unit
P <sub>DISS</sub>	Power Dissipation* (T <sub>c</sub> ≤ 50°C)	167	W
I <sub>c</sub>	Device Current*	8.0	A
V <sub>CC</sub>	Collector-Supply Voltage*	46	V
T <sub>J</sub>	Junction Temperature (Pulsed RF Operation)	250	°C
T <sub>STG</sub>	Storage Temperature	- 65 to +200	°C

### THERMAL DATA

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance*	1.2	°C/W
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\*Applies only to rated RF amplifier operation

# AM83135-040

## ELECTRICAL SPECIFICATIONS (T<sub>case</sub> = 25°C)

### STATIC

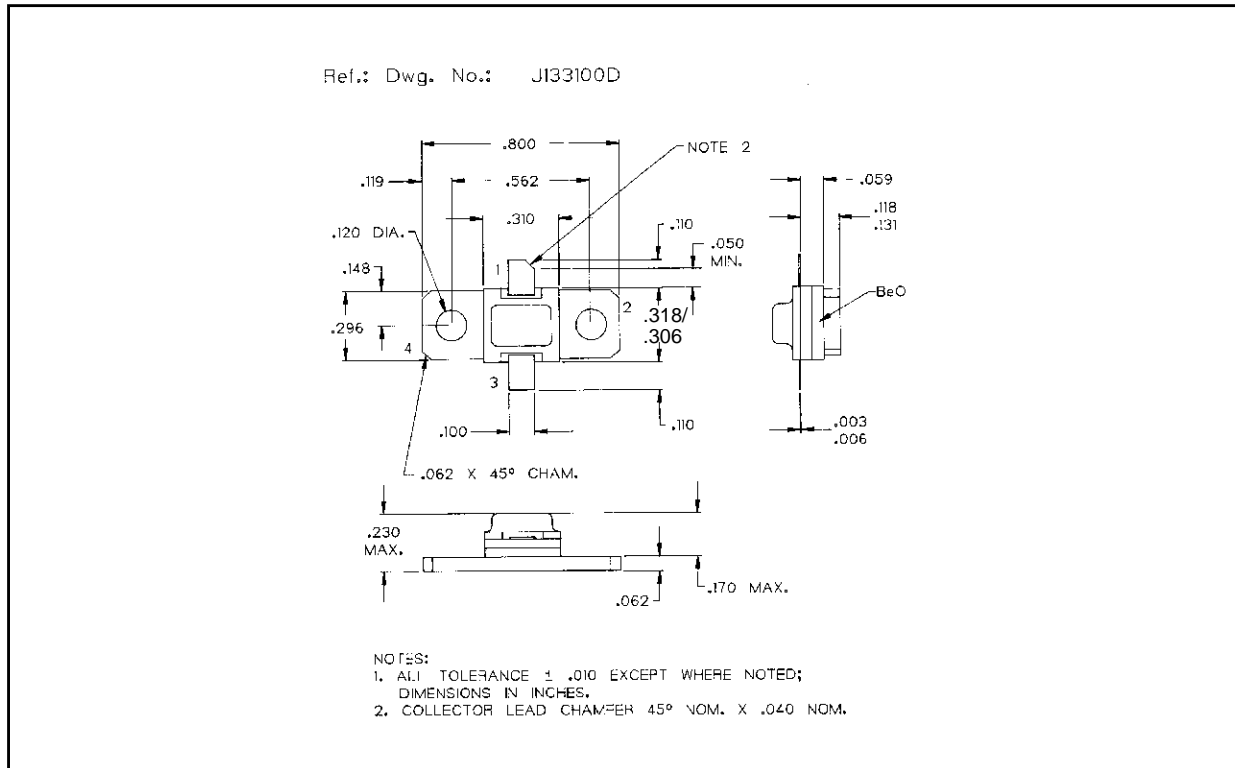
Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
BV <sub>CBO</sub>	I <sub>C</sub> = 25mA	I <sub>E</sub> = 0mA	55	—	—	V
BV <sub>EBO</sub>	I <sub>E</sub> = 5mA	I <sub>C</sub> = 0mA	3.5	—	—	V
BV <sub>CER</sub>	I <sub>C</sub> = 25mA	R <sub>BE</sub> = 10Ω	55	—	—	V
I <sub>CES</sub>	V <sub>BE</sub> = 0V	V <sub>CE</sub> = 40V	—	—	20	mA
h <sub>FE</sub>	V <sub>CE</sub> = 5V	I <sub>C</sub> = 3A	30	—	300	—

### DYNAMIC

Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
P <sub>OUT</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 12.5W	V <sub>CC</sub> = 40V	40	—	—	W
η <sub>c</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 12.5W	V <sub>CC</sub> = 40V	30	—	—	%
G <sub>P</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 12.5W	V <sub>CC</sub> = 40V	5.1	—	—	dB

Note: Pulse Width = 100μS  
Duty Cycle = 10%

## PACKAGE MECHANICAL DATA



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